



Welcome to [E-XFL.COM](#)

### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Discontinued at Digi-Key
Core Processor	CIP-51 8051
Core Size	8-Bit
Speed	50MHz
Connectivity	I <sup>2</sup> C, SMBus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	29
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 20x10/12b SAR; D/A 4x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-QFN (4x4)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/silicon-labs/efm8bb31f64g-a-qfn32">https://www.e-xfl.com/product-detail/silicon-labs/efm8bb31f64g-a-qfn32</a>

## 1. Feature List

The EFM8BB3 device family are fully integrated, mixed-signal system-on-a-chip MCUs. Highlighted features are listed below.

- Core:
  - Pipelined CIP-51 Core
  - Fully compatible with standard 8051 instruction set
  - 70% of instructions execute in 1-2 clock cycles
  - 50 MHz maximum operating frequency
- Memory:
  - Up to 64 kB flash memory (63 kB user-accessible), in-system re-programmable from firmware in 512-byte sectors
  - Up to 4352 bytes RAM (including 256 bytes standard 8051 RAM and 4096 bytes on-chip XRAM)
- Power:
  - Internal LDO regulator for CPU core voltage
  - Power-on reset circuit and brownout detectors
- I/O: Up to 29 total multifunction I/O pins:
  - Up to 25 pins 5 V tolerant under bias
  - Selectable state retention through reset events
  - Flexible peripheral crossbar for peripheral routing
  - 5 mA source, 12.5 mA sink allows direct drive of LEDs
- Clock Sources:
  - Internal 49 MHz oscillator with accuracy of  $\pm 1.5\%$
  - Internal 24.5 MHz oscillator with  $\pm 2\%$  accuracy
  - Internal 80 kHz low-frequency oscillator
  - External CMOS clock option
  - External crystal/RC/C Oscillator (up to 25 MHz)
- Analog:
  - 12/10-Bit Analog-to-Digital Converter (ADC)
  - Internal temperature sensor
  - 2 x 12-Bit Digital-to-Analog Converters (DAC)
  - 2 x Low-current analog comparators with adjustable reference
- Communications and Digital Peripherals:
  - 2 x UART, up to 3 Mbaud
  - SPI™ Master / Slave, up to 12 Mbps
  - SMBus™/I2C™ Master / Slave, up to 400 kbps
  - I2C High-Speed Slave, up to 3.4 Mbps
  - 16-bit CRC unit, supporting automatic CRC of flash at 256-byte boundaries
  - 4 Configurable Logic Units
- Timers/Counters and PWM:
  - 6-channel programmable counter array (PCA) supporting PWM, capture/compare, and frequency output modes
  - 6 x 16-bit general-purpose timers
  - Independent watchdog timer, clocked from the low frequency oscillator
- On-Chip, Non-Intrusive Debugging
  - Full memory and register inspection
  - Four hardware breakpoints, single-stepping

With on-chip power-on reset, voltage supply monitor, watchdog timer, and clock oscillator, the EFM8BB3 devices are truly standalone system-on-a-chip solutions. The flash memory is reprogrammable in-circuit, providing nonvolatile data storage and allowing field upgrades of the firmware. The on-chip debugging interface (C2) allows non-intrusive (uses no on-chip resources), full speed, in-circuit debugging using the production MCU installed in the final application. This debug logic supports inspection and modification of memory and registers, setting breakpoints, single stepping, and run and halt commands. All analog and digital peripherals are fully functional while debugging. Device operation is specified from 2.2 V up to a 3.6 V supply. Devices are AEC-Q100 qualified (pending) and available in 4x4 mm 32-pin QFN, 3x3 mm 24-pin QFN, 32-pin QFP, or 24-pin QSOP packages. All package options are lead-free and RoHS compliant.

## Timers (Timer 0, Timer 1, Timer 2, Timer 3, Timer 4, and Timer 5)

Several counter/timers are included in the device: two are 16-bit counter/timers compatible with those found in the standard 8051, and the rest are 16-bit auto-reload timers for timing peripherals or for general purpose use. These timers can be used to measure time intervals, count external events and generate periodic interrupt requests. Timer 0 and Timer 1 are nearly identical and have four primary modes of operation. The other timers offer both 16-bit and split 8-bit timer functionality with auto-reload and capture capabilities.

Timer 0 and Timer 1 include the following features:

- Standard 8051 timers, supporting backwards-compatibility with firmware and hardware.
- Clock sources include SYSCLK, SYSCLK divided by 12, 4, or 48, the External Clock divided by 8, or an external pin.
- 8-bit auto-reload counter/timer mode
- 13-bit counter/timer mode
- 16-bit counter/timer mode
- Dual 8-bit counter/timer mode (Timer 0)

Timer 2, Timer 3, Timer 4, and Timer 5 are 16-bit timers including the following features:

- Clock sources for all timers include SYSCLK, SYSCLK divided by 12, or the External Clock divided by 8
- LFOSC0 divided by 8 may be used to clock Timer 3 and Timer 4 in active or suspend/snooze power modes
- Timer 4 is a low-power wake source, and can be chained together with Timer 3
- 16-bit auto-reload timer mode
- Dual 8-bit auto-reload timer mode
- External pin capture
- LFOSC0 capture
- Comparator 0 capture
- Configurable Logic output capture

## Watchdog Timer (WDT0)

The device includes a programmable watchdog timer (WDT) running off the low-frequency oscillator. A WDT overflow forces the MCU into the reset state. To prevent the reset, the WDT must be restarted by application software before overflow. If the system experiences a software or hardware malfunction preventing the software from restarting the WDT, the WDT overflows and causes a reset. Following a reset, the WDT is automatically enabled and running with the default maximum time interval. If needed, the WDT can be disabled by system software or locked on to prevent accidental disabling. Once locked, the WDT cannot be disabled until the next system reset. The state of the RST pin is unaffected by this reset.

The Watchdog Timer has the following features:

- Programmable timeout interval
- Runs from the low-frequency oscillator
- Lock-out feature to prevent any modification until a system reset

## 3.6 Communications and Other Digital Peripherals

### Universal Asynchronous Receiver/Transmitter (UART0)

UART0 is an asynchronous, full duplex serial port offering modes 1 and 3 of the standard 8051 UART. Enhanced baud rate support allows a wide range of clock sources to generate standard baud rates. Received data buffering allows UART0 to start reception of a second incoming data byte before software has finished reading the previous data byte.

The UART module provides the following features:

- Asynchronous transmissions and receptions
- Baud rates up to SYSCLK/2 (transmit) or SYSCLK/8 (receive)
- 8- or 9-bit data
- Automatic start and stop generation
- Single-byte buffer on transmit and receive

## Low Current Comparators (CMP0, CMP1)

An analog comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. External input connections to device I/O pins and internal connections are available through separate multiplexers on the positive and negative inputs. Hysteresis, response time, and current consumption may be programmed to suit the specific needs of the application.

The comparator includes the following features:

- Up to 10 (CMP0) or 9 (CMP1) external positive inputs
- Up to 10 (CMP0) or 9 (CMP1) external negative inputs
- Additional input options:
  - Internal connection to LDO output
  - Direct connection to GND
  - Direct connection to VDD
  - Dedicated 6-bit reference DAC
- Synchronous and asynchronous outputs can be routed to pins via crossbar
- Programmable hysteresis between 0 and  $\pm 20$  mV
- Programmable response time
- Interrupts generated on rising, falling, or both edges
- PWM output kill feature

## 3.8 Reset Sources

Reset circuitry allows the controller to be easily placed in a predefined default condition. On entry to this reset state, the following occur:

- The core halts program execution.
- Module registers are initialized to their defined reset values unless the bits reset only with a power-on reset.
- External port pins are forced to a known state.
- Interrupts and timers are disabled.

All registers are reset to the predefined values noted in the register descriptions unless the bits only reset with a power-on reset. The contents of RAM are unaffected during a reset; any previously stored data is preserved as long as power is not lost. By default, the Port I/O latches are reset to 1 in open-drain mode, with weak pullups enabled during and after the reset. Optionally, firmware may configure the port I/O, DAC outputs, and precision reference to maintain state through system resets other than power-on resets. For Supply Monitor and power-on resets, the RSTb pin is driven low until the device exits the reset state. On exit from the reset state, the program counter (PC) is reset, and the system clock defaults to an internal oscillator. The Watchdog Timer is enabled, and program execution begins at location 0x0000.

Reset sources on the device include the following:

- Power-on reset
- External reset pin
- Comparator reset
- Software-triggered reset
- Supply monitor reset (monitors VDD supply)
- Watchdog timer reset
- Missing clock detector reset
- Flash error reset

## 3.9 Debugging

The EFM8BB3 devices include an on-chip Silicon Labs 2-Wire (C2) debug interface to allow flash programming and in-system debugging with the production part installed in the end application. The C2 interface uses a clock signal (C2CK) and a bi-directional C2 data signal (C2D) to transfer information between the device and a host system. See the C2 Interface Specification for details on the C2 protocol.

#### 4.1.11 Temperature Sensor

**Table 4.11. Temperature Sensor**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Offset	$V_{OFF}$	$T_A = 0\text{ }^{\circ}\text{C}$	—	TBD	—	mV
Offset Error <sup>1</sup>	$E_{OFF}$	$T_A = 0\text{ }^{\circ}\text{C}$	—	TBD	—	mV
Slope	M		—	TBD	—	mV/ $^{\circ}\text{C}$
Slope Error <sup>1</sup>	$E_M$		—	TBD	—	$\mu\text{V}/^{\circ}\text{C}$
Linearity			—	TBD	—	$^{\circ}\text{C}$
Turn-on Time			—	TBD	—	$\mu\text{s}$

**Note:**

1. Represents one standard deviation from the mean.

#### 4.1.12 DACs

Table 4.12. DACs

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Resolution	$N_{\text{bits}}$		12			Bits
Throughput Rate	$f_S$		—	—	200	ksps
Integral Nonlinearity	INL		TBD	$\pm 0.5$	TBD	LSB
Differential Nonlinearity	DNL		TBD	$\pm 5$	TBD	LSB
Output Noise	$V_{\text{REF}} = 2.4 \text{ V}$ $f_S = 0.1 \text{ Hz to } 300 \text{ kHz}$		—	110	—	$\mu\text{V}_{\text{RMS}}$
Slew Rate	SLEW		—	$\pm 1$	—	V/ $\mu\text{s}$
Output Settling Time to 1 LSB	$t_{\text{SETTLE}}$	$V_{\text{OUT}}$ change between 25% and 75% Full Scale	—	2.6	5	$\mu\text{s}$
Power-on Time	$t_{\text{PWR}}$		—	—	10	$\mu\text{s}$
Voltage Reference Range	$V_{\text{REF}}$		1.15	—	$V_{\text{DD}}$	V
Power Supply Rejection Ratio	PSRR	DC, $V_{\text{OUT}} = 50\%$ Full Scale	—	110	—	dB
		1 kHz, $V_{\text{OUT}} = 50\%$ Full Scale	—	60	—	dB
Total Harmonic Distortion	THD	$V_{\text{OUT}} = 10 \text{ kHz}$ sine wave, 10% to 90%	60	—	—	dB
Offset Error	$E_{\text{OFF}}$	$V_{\text{REF}} = 2.4 \text{ V}$	TBD	$\pm 0.5$	TBD	LSB
Offset Temperature Coefficient	$TC_{\text{OFF}}$		—	TBD	—	ppm/ $^{\circ}\text{C}$
Full-Scale Error	$E_{\text{FS}}$	$V_{\text{REF}} = 2.4 \text{ V}$	TBD	$\pm 5$	TBD	LSB
Full-Scale Error Tempco	$TC_{\text{FS}}$		—	TBD	—	ppm/ $^{\circ}\text{C}$
External Load Impedance	$R_{\text{LOAD}}$		2	—	—	k $\Omega$
External Load Capacitance	$C_{\text{LOAD}}$		TBD	—	100	pF
Load Regulation		$V_{\text{OUT}} = 50\%$ Full Scale $I_{\text{OUT}} = -2 \text{ to } 2 \text{ mA}$	—	100	TBD	$\mu\text{V}/\text{mA}$

#### 4.1.15 Port I/O

Table 4.15. Port I/O

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output High Voltage (High Drive)	$V_{OH}$	$I_{OH} = -7 \text{ mA}$ , $V_{IO} \geq 3.0 \text{ V}$	$V_{IO} - 0.7$	—	—	V
		$I_{OH} = -3.3 \text{ mA}$ , $2.2 \text{ V} \leq V_{IO} < 3.0 \text{ V}$	$V_{IO} \times 0.8$	—	—	V
		$I_{OH} = -1.8 \text{ mA}$ , $1.71 \text{ V} \leq V_{IO} < 2.2 \text{ V}$				
Output Low Voltage (High Drive)	$V_{OL}$	$I_{OL} = 13.5 \text{ mA}$ , $V_{IO} \geq 3.0 \text{ V}$	—	—	0.6	V
		$I_{OL} = 7 \text{ mA}$ , $2.2 \text{ V} \leq V_{IO} < 3.0 \text{ V}$	—	—	$V_{IO} \times 0.2$	V
		$I_{OL} = 3.6 \text{ mA}$ , $1.71 \text{ V} \leq V_{IO} < 2.2 \text{ V}$				
Output High Voltage (Low Drive)	$V_{OH}$	$I_{OH} = -4.75 \text{ mA}$ , $V_{IO} \geq 3.0 \text{ V}$	$V_{IO} - 0.7$	—	—	V
		$I_{OH} = -2.25 \text{ mA}$ , $2.2 \text{ V} \leq V_{IO} < 3.0 \text{ V}$	$V_{IO} \times 0.8$	—	—	V
		$I_{OH} = -1.2 \text{ mA}$ , $1.71 \text{ V} \leq V_{IO} < 2.2 \text{ V}$				
Output Low Voltage (Low Drive)	$V_{OL}$	$I_{OL} = 6.5 \text{ mA}$ , $V_{IO} \geq 3.0 \text{ V}$	—	—	0.6	V
		$I_{OL} = 3.5 \text{ mA}$ , $2.2 \text{ V} \leq V_{IO} < 3.0 \text{ V}$	—	—	$V_{IO} \times 0.2$	V
		$I_{OL} = 1.8 \text{ mA}$ , $1.71 \text{ V} \leq V_{IO} < 2.2 \text{ V}$				
Input High Voltage	$V_{IH}$		$0.7 \times V_{IO}$	—	—	V
Input Low Voltage	$V_{IL}$		—	—	$0.3 \times V_{IO}$	V
Pin Capacitance	$C_{IO}$		—	7	—	pF
Weak Pull-Up Current ( $V_{IN} = 0 \text{ V}$ )	$I_{PU}$	$V_{DD} = 3.6$	-30	-20	-10	$\mu\text{A}$
Input Leakage (Pullups off or Analog)	$I_{LK}$	$\text{GND} < V_{IN} < V_{IO}$	TBD	—	TBD	$\mu\text{A}$
Input Leakage Current with $V_{IN}$ above $V_{IO}$	$I_{LK}$	$V_{IO} < V_{IN} < V_{IO} + 2.5 \text{ V}$ Any pin except P3.0, P3.1, P3.2, or P3.3	0	5	150	$\mu\text{A}$

## 6. Pin Definitions

### 6.1 EFM8BB3x-QFN32 Pin Definitions

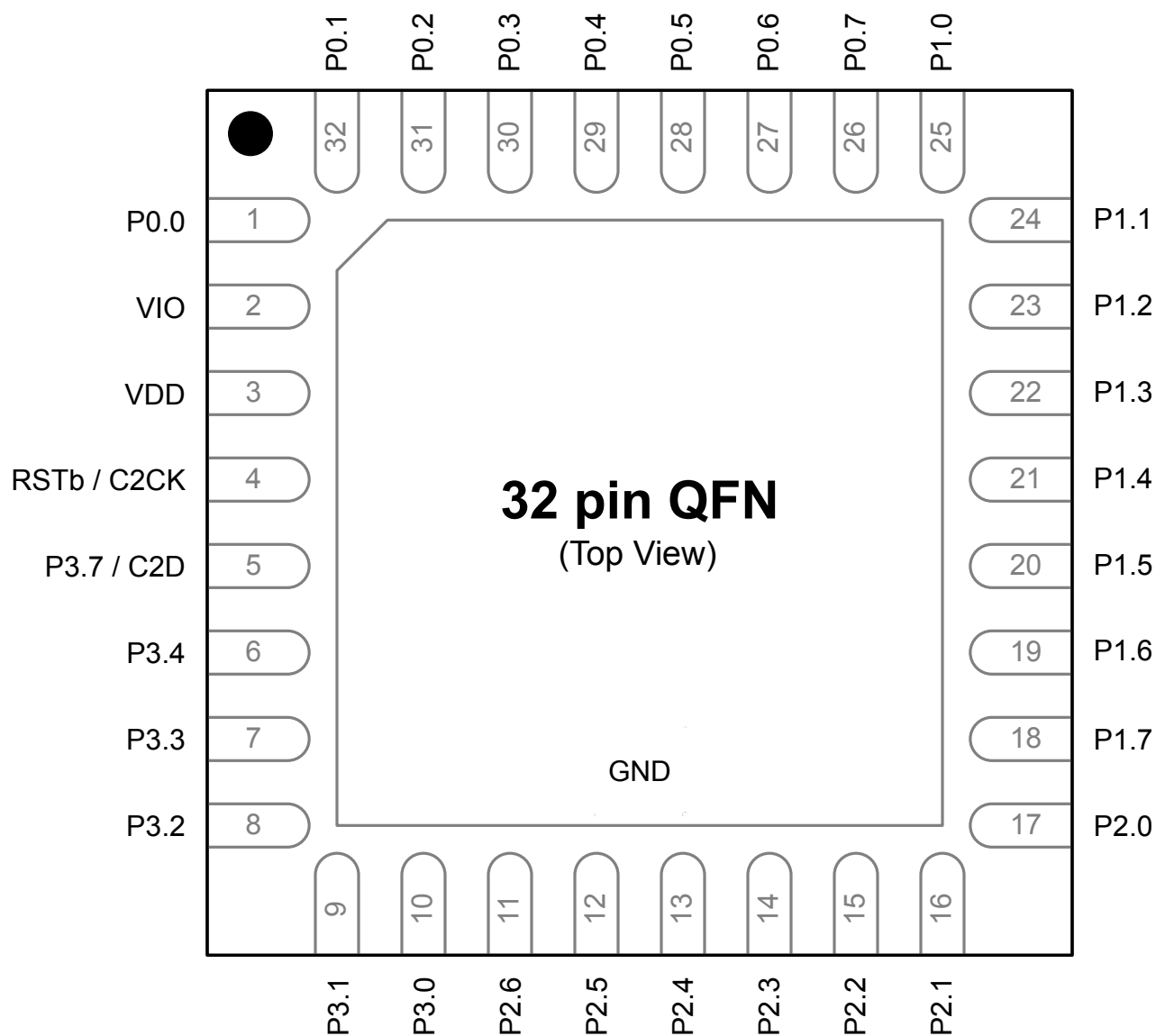


Figure 6.1. EFM8BB3x-QFN32 Pinout



**Table 6.1. Pin Definitions for EFM8BB3x-QFN32**

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
1	P0.0	Multifunction I/O	Yes	P0MAT.0 INT0.0 INT1.0 CLU0A.8 CLU2A.8 CLU3B.8	VREF
2	VIO	I/O Supply Power Input			
3	VDD	Supply Power Input			
4	RSTb / C2CK	Active-low Reset / C2 Debug Clock			
5	P3.7 / C2D	Multifunction I/O / C2 Debug Data			
6	P3.4	Multifunction I/O			
7	P3.3	Multifunction I/O			DAC3
8	P3.2	Multifunction I/O			DAC2
9	P3.1	Multifunction I/O			DAC1
10	P3.0	Multifunction I/O			DAC0
11	P2.6	Multifunction I/O			ADC0.19 CMP1P.8 CMP1N.8
12	P2.5	Multifunction I/O		CLU3OUT	ADC0.18 CMP1P.7 CMP1N.7
13	P2.4	Multifunction I/O			ADC0.17 CMP1P.6 CMP1N.6
14	P2.3	Multifunction I/O	Yes	P2MAT.3 CLU1B.15 CLU2B.15 CLU3A.15	ADC0.16 CMP1P.5 CMP1N.5

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
15	P2.2	Multifunction I/O	Yes	P2MAT.2 CLU2OUT CLU1A.15 CLU2B.14 CLU3A.14	ADC0.15 CMP1P.4 CMP1N.4
16	P2.1	Multifunction I/O	Yes	P2MAT.1 I2C0_SCL CLU1B.14 CLU2A.15 CLU3B.15	ADC0.14 CMP1P.3 CMP1N.3
17	P2.0	Multifunction I/O	Yes	P2MAT.0 I2C0_SDA CLU1A.14 CLU2A.14 CLU3B.14	CMP1P.2 CMP1N.2
18	P1.7	Multifunction I/O	Yes	P1MAT.7 CLU0B.15 CLU1B.13 CLU2A.13	ADC0.13 CMP0P.9 CMP0N.9
19	P1.6	Multifunction I/O	Yes	P1MAT.6 CLU0A.15 CLU1B.12 CLU2A.12	ADC0.12
20	P1.5	Multifunction I/O	Yes	P1MAT.5 CLU0B.14 CLU1A.13 CLU2B.13 CLU3B.11	ADC0.11
21	P1.4	Multifunction I/O	Yes	P1MAT.4 CLU0A.14 CLU1A.12 CLU2B.12 CLU3B.10	ADC0.10

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
28	P0.5	Multifunction I/O	Yes	P0MAT.5 INT0.5 INT1.5 UART0_RX CLU0B.10 CLU1A.9	ADC0.3 CMP0P.3 CMP0N.3
29	P0.4	Multifunction I/O	Yes	P0MAT.4 INT0.4 INT1.4 UART0_TX CLU0A.10 CLU1A.8	ADC0.2 CMP0P.2 CMP0N.2
30	P0.3	Multifunction I/O	Yes	P0MAT.3 EXTCLK INT0.3 INT1.3 CLU0B.9 CLU2B.10 CLU3A.9	XTAL2
31	P0.2	Multifunction I/O	Yes	P0MAT.2 INT0.2 INT1.2 CLU0OUT CLU0A.9 CLU2B.8 CLU3A.8	XTAL1 ADC0.1 CMP0P.1 CMP0N.1
32	P0.1	Multifunction I/O	Yes	P0MAT.1 INT0.1 INT1.1 CLU0B.8 CLU2A.9 CLU3B.9	ADC0.0 CMP0P.0 CMP0N.0 AGND
Center	GND	Ground			

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
6	P3.7 / C2D	Multifunction I/O / C2 Debug Data			
7	P3.3	Multifunction I/O			DAC3
8	P3.2	Multifunction I/O			DAC2
9	P3.1	Multifunction I/O			DAC1
10	P3.0	Multifunction I/O			DAC0
11	P2.6	Multifunction I/O			ADC0.19 CMP1P.8 CMP1N.8
12	P2.5	Multifunction I/O		CLU3OUT	ADC0.18 CMP1P.7 CMP1N.7
13	P2.4	Multifunction I/O			ADC0.17 CMP1P.6 CMP1N.6
14	P2.3	Multifunction I/O	Yes	P2MAT.3 CLU1B.15 CLU2B.15 CLU3A.15	ADC0.16 CMP1P.5 CMP1N.5
15	P2.2	Multifunction I/O	Yes	P2MAT.2 CLU2OUT CLU1A.15 CLU2B.14 CLU3A.14	ADC0.15 CMP1P.4 CMP1N.4
16	P2.1	Multifunction I/O	Yes	P2MAT.1 I2C0_SCL CLU1B.14 CLU2A.15 CLU3B.15	ADC0.14 CMP1P.3 CMP1N.3
17	P2.0	Multifunction I/O	Yes	P2MAT.0 I2C0_SDA CLU1A.14 CLU2A.14 CLU3B.14	CMP1P.2 CMP1N.2

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
25	P1.0	Multifunction I/O	Yes	P1MAT.0 CLU1OUT CLU0A.12 CLU1A.10 CLU2A.10	ADC0.6 CMP0P.6 CMP0N.6 CMP1P.1 CMP1N.1
26	P0.7	Multifunction I/O	Yes	P0MAT.7 INT0.7 INT1.7 CLU0B.11 CLU1B.9 CLU3A.11	ADC0.5 CMP0P.5 CMP0N.5 CMP1P.0 CMP1N.0
27	P0.6	Multifunction I/O	Yes	P0MAT.6 CNVSTR INT0.6 INT1.6 CLU0A.11 CLU1B.8 CLU3A.10	ADC0.4 CMP0P.4 CMP0N.4
28	P0.5	Multifunction I/O	Yes	P0MAT.5 INT0.5 INT1.5 UART0_RX CLU0B.10 CLU1A.9	ADC0.3 CMP0P.3 CMP0N.3
29	P0.4	Multifunction I/O	Yes	P0MAT.4 INT0.4 INT1.4 UART0_TX CLU0A.10 CLU1A.8	ADC0.2 CMP0P.2 CMP0N.2

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
19	P0.7	Multifunction I/O	Yes	P0MAT.7 INT0.7 INT1.7 CLU1OUT CLU0B.11 CLU1B.9 CLU3A.11	ADC0.5 CMP0P.5 CMP0N.5 CMP1P.1 CMP1N.1
20	P0.6	Multifunction I/O	Yes	P0MAT.6 CNVSTR INT0.6 INT1.6 CLU0A.11 CLU1B.8 CLU3A.10	ADC0.4 CMP0P.4 CMP0N.4 CMP1P.0 CMP1N.0
21	P0.5	Multifunction I/O	Yes	P0MAT.5 INT0.5 INT1.5 UART0_RX CLU0B.10 CLU1A.9	ADC0.3 CMP0P.3 CMP0N.3
22	P0.4	Multifunction I/O	Yes	P0MAT.4 INT0.4 INT1.4 UART0_TX CLU0A.10 CLU1A.8	ADC0.2 CMP0P.2 CMP0N.2
23	P0.3	Multifunction I/O	Yes	P0MAT.3 EXTCLK INT0.3 INT1.3 CLU0B.9 CLU2B.10 CLU3A.9	XTAL2

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
24	P0.2	Multifunction I/O	Yes	P0MAT.2 INT0.2 INT1.2 CLU0OUT CLU0A.9 CLU2B.8 CLU3A.8	XTAL1 ADC0.1 CMP0P.1 CMP0N.1
Center	GND	Ground			

## 6.4 EFM8BB3x-QSOP24 Pin Definitions

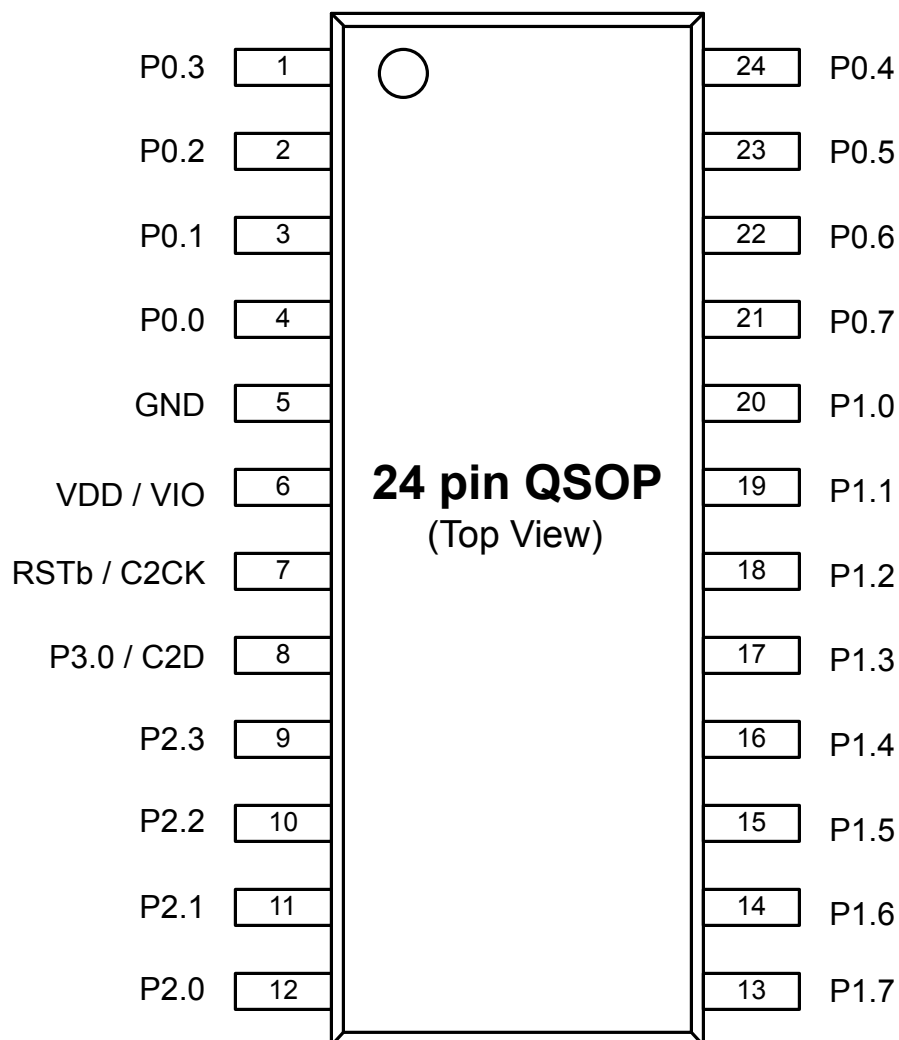


Figure 6.4. EFM8BB3x-QSOP24 Pinout

Table 6.4. Pin Definitions for EFM8BB3x-QSOP24

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
1	P0.3	Multifunction I/O	Yes	P0MAT.3 EXTCLK INT0.3 INT1.3 CLU0B.9 CLU2B.10 CLU3A.9	XTAL2



Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
11	P2.1	Multifunction I/O	Yes	P2MAT.1 CLU1B.14 CLU2A.15 CLU3B.15	DAC1
12	P2.0	Multifunction I/O	Yes	P2MAT.0 CLU1A.14 CLU2A.14 CLU3B.14	DAC0
13	P1.7	Multifunction I/O	Yes	P1MAT.7 CLU0B.15 CLU1B.13 CLU2A.13	ADC0.12 CMP1P.6 CMP1N.6
14	P1.6	Multifunction I/O	Yes	P1MAT.6 CLU3OUT CLU0A.15 CLU1B.12 CLU2A.12	ADC0.11 CMP1P.5 CMP1N.5
15	P1.5	Multifunction I/O	Yes	P1MAT.5 CLU2OUT CLU0B.14 CLU1A.13 CLU2B.13 CLU3B.11	ADC0.10 CMP1P.4 CMP1N.4
16	P1.4	Multifunction I/O	Yes	P1MAT.4 I2C0_SCL CLU0A.14 CLU1A.12 CLU2B.12 CLU3B.10	ADC0.9 CMP1P.3 CMP1N.3
17	P1.3	Multifunction I/O	Yes	P1MAT.3 I2C0_SDA CLU0B.13 CLU1B.11 CLU2B.11 CLU3A.13	CMP1P.2 CMP1N.2

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
18	P1.2	Multifunction I/O	Yes	P1MAT.2 CLU0A.13 CLU1A.11 CLU2B.10 CLU3A.12 CLU3B.13	ADC0.8
19	P1.1	Multifunction I/O	Yes	P1MAT.1 CLU0B.12 CLU1B.10 CLU2A.11 CLU3B.12	ADC0.7
20	P1.0	Multifunction I/O	Yes	P1MAT.0 CLU0A.12 CLU1A.10 CLU2A.10	ADC0.6
21	P0.7	Multifunction I/O	Yes	P0MAT.7 INT0.7 INT1.7 CLU1OUT CLU0B.11 CLU1B.9 CLU3A.11	ADC0.5 CMP0P.5 CMP0N.5 CMP1P.1 CMP1N.1
22	P0.6	Multifunction I/O	Yes	P0MAT.6 CNVSTR INT0.6 INT1.6 CLU0A.11 CLU1B.8 CLU3A.10	ADC0.4 CMP0P.4 CMP0N.4 CMP1P.0 CMP1N.0
23	P0.5	Multifunction I/O	Yes	P0MAT.5 INT0.5 INT1.5 UART0_RX CLU0B.10 CLU1A.9	ADC0.3 CMP0P.3 CMP0N.3

## 7. QFN32 Package Specifications

### 7.1 QFN32 Package Dimensions

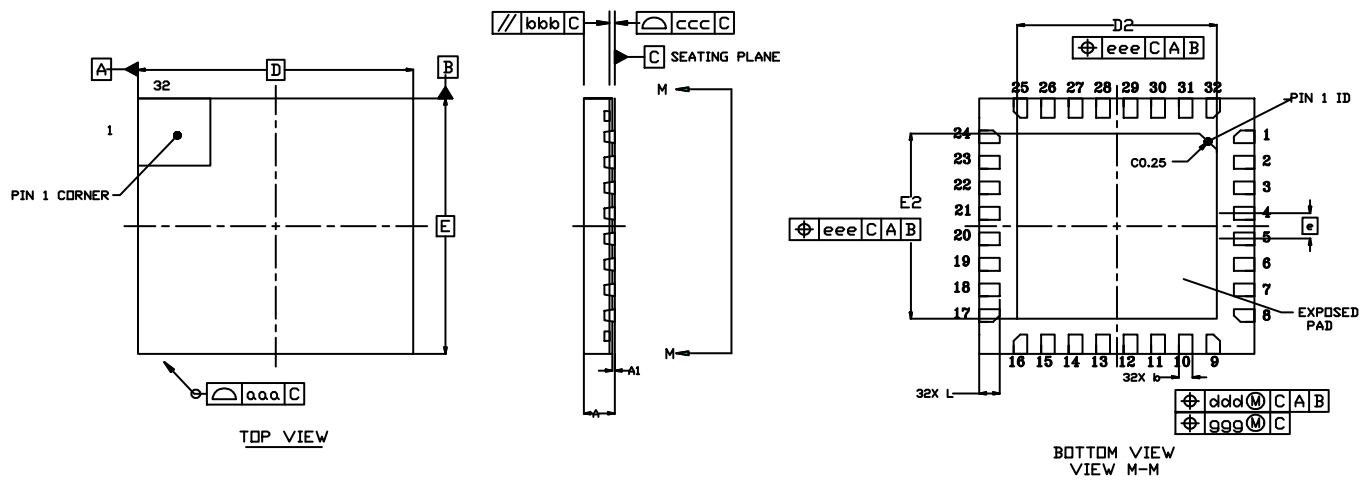


Figure 7.1. QFN32 Package Drawing

Table 7.1. QFN32 Package Dimensions

Dimension	Min	Typ	Max
A	0.45	0.50	0.55
A1	0.00	0.035	0.05
b	0.15	0.20	0.25
D	4.00 BSC.		
D2	2.80	2.90	3.00
e	0.40 BSC.		
E	4.00 BSC.		
E2	2.80	2.90	3.00
L	0.20	0.30	0.40
aaa	—	—	0.10
bbb	—	—	0.10
ccc	—	—	0.08
ddd	—	—	0.10
eee	—	—	0.10
ggg	—	—	0.05

Dimension	Min	Typ	Max
<b>Note:</b> <ol style="list-style-type: none"> <li>All dimensions shown are in millimeters (mm) unless otherwise noted.</li> <li>Dimensioning and Tolerancing per ANSI Y14.5M-1994.</li> <li>This drawing conforms to JEDEC Solid State Outline MO-220.</li> <li>Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.</li> </ol>			

## 8.2 QFP32 PCB Land Pattern

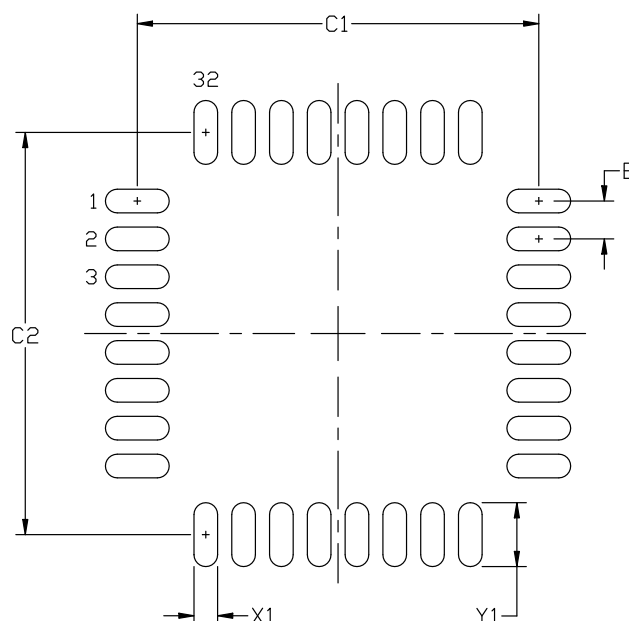


Figure 8.2. QFP32 PCB Land Pattern Drawing

Table 8.2. QFP32 PCB Land Pattern Dimensions

Dimension	Min	Max
C1	8.40	8.50
C2	8.40	8.50
E	0.80 BSC	
X1	0.55	
Y1	1.5	

**Note:**

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.
3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60  $\mu\text{m}$  minimum, all the way around the pad.
4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
5. The stencil thickness should be 0.125 mm (5 mils).
6. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
7. A No-Clean, Type-3 solder paste is recommended.
8. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.